

Appl. No. 10/710,437
Amdt. dated January 26, 2006
Reply to Office action of November 01, 2005

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A lumped-element diplexer implemented in a multi-layered substrate comprising:
 - 5 a low-pass filter circuit wherein circuit elements are disposed on a first series of layers of the multi-layered substrate and wherein a first end of the low-pass filter circuit is connected to a first port and a second end of the low-pass filter circuit is connected to a second port;
 - 10 a high-pass filter circuit wherein circuit elements are disposed on a second series of layers of the multi-layered substrate and wherein a first end of the high-pass filter circuit is connected to [[a]] the first port and a second end of the high-pass filter circuit is connected to a third port; and
 - 15 a ground plane forming a base of the multi-layered substrate, wherein elements of the filter circuits are orientated horizontally with respect to the ground plane and are arranged in layers aligned substantially vertically, these layers being separated by a dielectric material and inter-layer connections being implemented by at least a via;
 - 20 wherein no layer is between an uppermost layer of the first series of layers of the multi-layered substrate is immediately adjacent to and a lowermost layer of the second series of layers of the multi-layered substrate.
2. (Cancelled)
3. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 1, wherein:
 - 25 the low-pass filter circuit comprises:
 - a first capacitor plate disposed on a first layer of the multi-layered substrate;
 - a second capacitor plate disposed on a second layer of the multi-layered

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substrate; and

a first inductor plate directly disposed on a third layer of the multi-layered substrate;

wherein the first capacitor plate is connected to the first port, the second capacitor plate is connected to a first end of the first inductor plate and the second port via a third capacitor plate of the high-pass filter circuit, and a second end of the first inductor plate is connected to the first port; and

the high-pass filter circuit comprises:

10 a third capacitor plate disposed on a ~~forth~~ fourth layer of the multi-layered substrate;

a fourth capacitor plate disposed on a fifth layer of the multi-layered substrate;

a fifth capacitor plate disposed on a sixth layer of the multi-layered substrate; and

15 a second inductor plate directly disposed on a seventh layer of the multi-layered substrate;

wherein the third capacitor plate is connected to the second port, the ~~forth~~ fourth capacitor plate is connected to a first end of the second inductor plate, the fifth capacitor plate is connected to the third port and

20 a second end of the second inductor plate is connected to the ground plane.

4. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 1, wherein inductive the circuit elements of the filter circuits comprise inductive elements that comprise plates formed as spirals.

25 5. (Currently Amended) The lumped-element diplexer implemented in a multi-layered

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substrate of claim 1, wherein the circuit elements of the filter circuits comprise at least one inductive element of the filter circuits is formed on a plurality of layers of the multi-layered substrate.

5 6. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 1, wherein at least one capacitive element of the circuit elements of the filter circuits comprises at least one capacitive element comprising a plurality of plates formed on a plurality of layers of the multi-layered substrate.

10 7. (Original) The lumped-element diplexer implemented in a multi-layered substrate of claim 1, wherein the high-pass filter circuit further comprises a low frequency notch filter circuit.

15 8. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim [[7]] 3, wherein at least the third and fifth capacitor plates are dimensioned to have additional overlapping area in order to realize an additional capacitor equivalence.

20 9. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 1, wherein the ground plane forms a zeroth layer of the lumped-element diplexer.

25 10. (Original) The lumped-element diplexer implemented in a multi-layered substrate of claim 1, wherein the device is realized in a multi-layered, low temperature co-fired ceramic substrate.

11. (Currently Amended) A lumped-element diplexer implemented in a multi-layered substrate comprising:

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a low-pass filter circuit comprising:

5 a first capacitor plate disposed on a first layer of a first series of layers of the multi-layered substrate;

a second capacitor plate disposed on a second layer of [[a]] the first series of layers of the multi-layered substrate; and

10 a first inductor plate directly disposed on a third layer of [[a]] the first series of layers of the multi-layered substrate;

wherein the first capacitor plate is connected to a first port, the second capacitor plate is connected to a first end of the first inductor plate and to a second port via a third capacitor plate of a high-pass filter circuit of the lumped-element diplexer, and a second end of the first inductor plate is connected to the first port; and

15 a high-pass filter circuit comprising:

a third capacitor plate disposed on a first layer of a second series of layers of the multi-layered substrate;

a fourth capacitor plate disposed on a second layer of [[a]] the second series of layers of the multi-layered substrate;

a fifth capacitor plate disposed on a third layer of [[a]] the second series of layers of the multi-layered substrate; and

20 a second inductor plate directly disposed on a ~~forth~~ fourth layer of [[a]] the second series of layers of the multi-layered substrate;

wherein the third capacitor plate is connected to the second port, the ~~forth~~ fourth capacitor plate is connected to a first end of the second inductor plate, the fifth capacitor plate is connected to a third port and a second end of the second inductor plate is connected to a ground plane of the lumped-element diplexer, and wherein the high-pass filter circuit further comprises a low frequency notch filter circuit realized by additional overlapping area of the third and fifth capacitor plates.

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a ground plane forming a base of the multi-layered substrate, wherein elements of the filter circuits are orientated horizontally with respect to the ground plane and are arranged in layers aligned substantially vertically, these layers being separated by a dielectric material and inter-layer connections being implemented by at least a via;

5 wherein no layer is between an uppermost layer of the first series of layers of the multi-layered substrate ~~is immediately adjacent to and~~ a lowermost layer of the second series of layers of the multi-layered substrate.

10 12. (Cancelled)

13. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 11, wherein ~~inductive elements of the filter circuits comprise plates formed as spirals an inductor plate comprises a spiral-shaped metal strip.~~

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14. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 11, ~~wherein further comprising~~ at least one inductive element of the filter circuits is formed on a plurality of layers of the multi-layered substrate.

20 15. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 11, ~~wherein further comprising~~ at least one capacitive element of the filter circuits comprises a plurality of plates formed on a plurality of layers of the multi-layered substrate.

25 16. (Currently Amended) The lumped-element diplexer implemented in a multi-layered substrate of claim 11, wherein the ground plane forms a zeroth layer of the lumped-element diplexer.